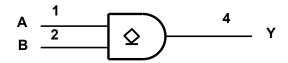


Logic Diagram



Functional Table

Inp	Output	
Α	В	Υ
Н	Н	Z
L	Х	L
Х	L	L

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-20	mA
I _{OK}	Output Clamp Current (V _O < 0 or V _O > V _{CC})	±20	mA
Io	Continuous output current (V _O = 0 to V _{CC})	±25	mA
I _{CC}	Continuous current through V _{CC}	50	mA
I _{GND}	Continuous current through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Note:

4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.



Recommended Operating Conditions (Note 5) (@TA = +25°C, unless otherwise specified.)

Symbol	F	Parameter	Min	Max	Unit
V _{CC}	Operating Voltage		2.0	5.5	V
		V _{CC} = 2V	1.5		
V_{IH}	High-Level Input Voltage	V _{CC} = 3V	2.1		V
		V _{CC} = 5.5V	3.85		
		V _{CC} = 2V		0.5	
V_{IL}	Low-Level input Voltage	V _{CC} = 3V		0.9	V
		V _{CC} = 5.5V		1.65	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	5.5	V
		V _{CC} = 2V		50	uA
loL	Low-Level Output Current	$V_{CC} = 5V \pm 0.5V$		4	mA
		V _{CC} = 3V		8	IIIA
Δt/ΔV	Input transition rise or fall rate	$V_{CC} = 3.3V \pm 0.3V$		100	ns/V
ΔυΔν	Input transition rise or fall rate	$V_{CC} = 5V \pm 0.5V$		20	115/ V
TA	Operating free-air temperature		-40	+125	°C

Note: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V		+25°C		-40°C to	o +85°C	-40°C to	+125°C	Unit
Symbol	Parameter	rest Conditions	V _{CC}	Min	Тур	Max	Min	Max	Min	Max	Unit
		2V			0.1		0.1		0.1		
		I _{OL} = 50μA	3V			0.1		0.1		0.1	
V_{OL}	High-level Input Voltage		4.5V			0.1		0.1		0.1	V
	Voltage	I _{OL} = 4mA	3V			0.36		0.44		0.55	
		I _{OL} = 8mA	4.5V			0.36		0.44		0.55	
II	Input Current	V _I = 5.5V or GND	0 to 5.5V			±0.1		±1		±2	μA
loz	Z-state Output Current	V _I = 5.5V or GND	0 to 5.5V			±0.25		±2.5		±10	μA
Icc	Supply Current	V _I = 5.5V or GND I _O =0	5.5V			1		10		40	μA
Ci	Input Capacitance	$V_i = V_{CC} - \text{or GND}$	5.5V		2.0	10		10		10	pF
	Thermal	SOT25			204						
θ_{JA}	Resistance Junction-to- Ambient	SOT353	(Note 6)		371						°C/W
	Thermal	SOT25			52						
$\theta_{ m JC}$	Resistance Junction-to-Case	SOT353	(Note 6)		143						°C/W

Note: 6. Test conditions for SOT25, and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

V_{CC} = **3.3V ±0.3** (see Figure 1)

Parameter	From	ТО			+25°C		-40°C to	o +85°C	-40°C to	+125°C	Unit	
Parameter	(Input)	(OUTPUT)		Min	Тур	Max	Min	Max	Min	Max	Ullit	
4	A 5	A or B	V	C _L = 15pF	0.6	4.6	7.5	0.6	8.5	0.6	9.0	ns
t _{pd}	AUIB	Ť	C _L = 50pF	0.6	6.5	11.0	0.6	12.0	0.6	12.5	ns	

 $V_{CC} = 5V \pm 0.5V$ (see Figure 1)

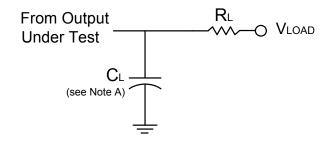
Parameter	From	то			+25°C		-40°C to	o +85°C	-40°C to	+125°C	Unit
Parameter	(Input)	(OUTPUT)		Min	Тур	Max	Min	Max	Min	Max	Ullit
4	A or B	V	C _L = 15pF	0.6	3.2	5.5	0.6	6.5	0.6	7.0	ns
τ _{pd}	AUID	ī	C _L = 50pF	0.6	4.6	7.5	0.6	8.0	0.6	8.5	ns

Operating Characteristics

 $T_A = +25$ °C

	Parameter	Test Conditions	V _{CC} = 5V Typ	Unit
C_{pd}	Power dissipation capacitance	f = 1 MHz No Load	5	pF

Parameter Measurement Information



TEST	Condition
t _{PLZ} (see Notes D and E)	V_{LOAD}
t _{PZL} (see Notes D and F)	V_{LOAD}

V	Inp	uts	V	V		Б	V Δ
V _{CC}	Vı	t _r /t _f	V _M	V_{LOAD}	CL	R_L	VA
3.3V ±0.3V	V _{CC}	≤3ns	V _{CC} /2	V _{CC}	15pF	1ΚΩ	0.3V
3.3V ±0.3V	V _{CC}	≤3ns	V _{CC} /2	V _{CC}	50pF	1ΚΩ	0.3V
5V ±0.5V	V _{CC}	≤3ns	V _{CC} /2	V _{CC}	15pF	1ΚΩ	0.3V
5V ±0.5V	V _{CC}	≤3ns	V _{CC} /2	V _{CC}	50pF	1ΚΩ	0.3V



Parameter Measurement Information (cont.)

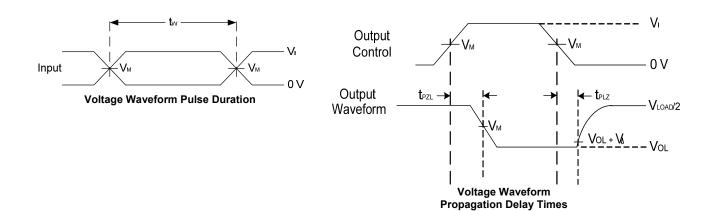


Figure 1 Load Circuit and Voltage Waveforms

Notes:

A. Includes test lead and test apparatus capacitance.
B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.
C. The inputs are measured one at a time with one transition per measurement.

D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD} .

E. t_{PZL} is measured at V_{M} .

F. t_{PLZ} is measured at V_{OL} + V_{Δ}



Ordering Information

T4AHC1G 09 XX - 7

Logic Device Function Package Packing

74 : Logic Prefix 09 : 2-Input W5 : SOT25 7 : Tape & Reel

AHC : 2 to 5.5V AND -Gate SE : SOT353

Family With Open
1G : One gate Drain Output

Part Number	Bookaga Cada	Dookaging	7" Tape	and Reel
Part Number	Package Code	Packaging	Quantity	Part Number Suffix
74AHC1G09W5-7	W5	SOT25	3000/Tape & Reel	-7
74AHC1G09SE-7	SE	SOT353	3000/Tape & Reel	-7

Marking Information

(Top View)

2 3 X: A~Z: Internal code

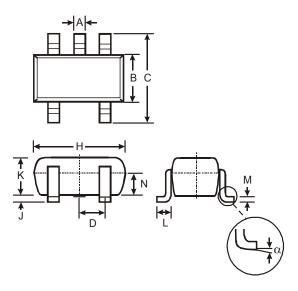
Part Number	Package	Identification Code
74AHC1G09W5	SOT25	YN
74AHC1G09SE	SOT353	YN



Package Outline Dimensions (All dimensions in mm.)

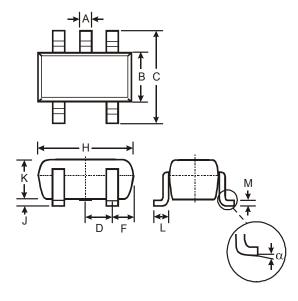
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

(1) Package Type: SOT25



	SOT25							
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
С	2.70	3.00	2.80					
D	_		0.95					
Н	2.90	3.10	3.00					
J	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
N	0.70	0.80	0.75					
α	0°	8°	_					
All D	imensi	ons in	mm					

(2) Package Type: SOT353



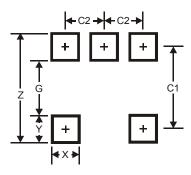
SOT353		
Dim	Min	Max
Α	0.10	0.30
В	1.15	1.35
С	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
Н	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		



Suggested Pad Layout

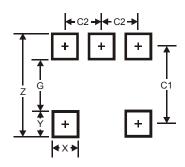
Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

(1) Package Type: SOT25



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65



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